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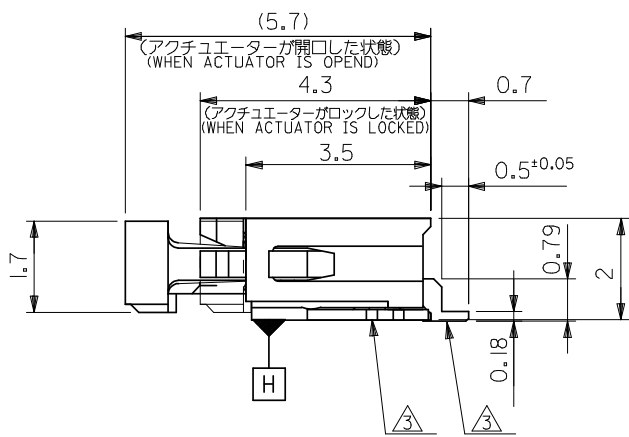
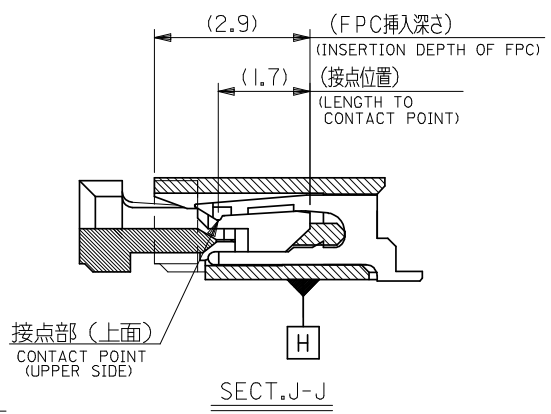
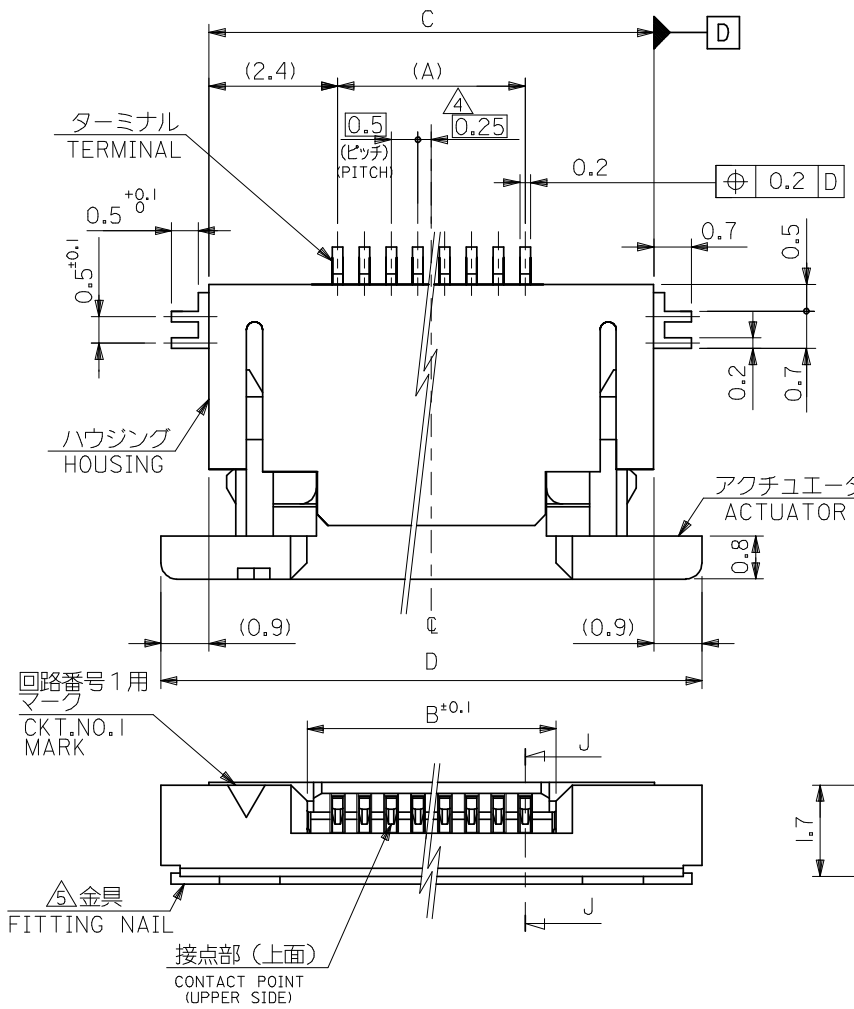
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注記 NOTES

1. 使用材料 MATERIAL
- | | |
|---------------------|--|
| ハウジング
HOUSING | : ポリアミド46、ガラス充填、UL94V-0 (白)
POLYAMIDE46, GLASS FILLED, UL94V-0(WHITE) |
| アクチュエータ
ACTUATOR | : ポリフェニレンサルファイド、ガラス充填、UL94V-0 (黒)
POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0(BLACK) |
| ターミナル
TERMINAL | : リン青銅、ニッケル下地銅ビスマスメッキ (t=0.2)
PHOSPOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING |
| 金具
FITTING NAIL | : リン青銅、ニッケル下地純銅メッキ (t=0.2)
PHOSPOR BRONZE, TIN OVER NICKEL PLATING |
2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 52745-**19 SHOULD BE LOCKED.
- △ ソルダテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX. 下方向 0.15 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM H UPPER DIRECTION: 0.1 MAX. , LOWER DIRECTION: 0.15 MAX.
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. 本製品は 52745-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52745-**17

16.1	14.3	10.65	9.5	52745-2096	52745-2019	20
15.6	13.8	10.15	9.0	-1996	-1919	19
15.1	13.3	9.65	8.5	-1896	-1819	18
14.6	12.8	9.15	8.0	-1796	-1719	17
14.1	12.3	8.65	7.5	-1696	-1619	16
13.6	11.8	8.15	7.0	-1596	-1519	15
13.1	11.3	7.65	6.5	-1496	-1419	14
12.6	10.8	7.15	6.0	-1396	-1319	13
12.1	10.3	6.65	5.5	-1296	-1219	12
11.6	9.8	6.15	5.0	-1196	-1119	11
11.1	9.3	5.65	4.5	-1096	-1019	10
10.6	8.8	5.15	4.0	-0996	-0919	9
10.1	8.3	4.65	3.5	-0896	-0819	8
9.6	7.8	4.15	3.0	-0796	-0719	7
9.1	7.3	3.65	2.5	-0696	-0619	6
8.1	6.3	2.65	1.5	52745-0496	52745-0419	4
D	C	B	(A)	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	極数 CIRCUIT

52745-**19 | MODEL NO.

REVISED EC NO: J2008-4308 DRWN: WABEI CHKD: THARUYAMA APPR: NUKITA B	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY T. UENO	DATE '04/01/28	TITLE 0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/01/28				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/01/28	 MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.					DOCUMENT NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52745-048			SHEET NO. 1 OF 2
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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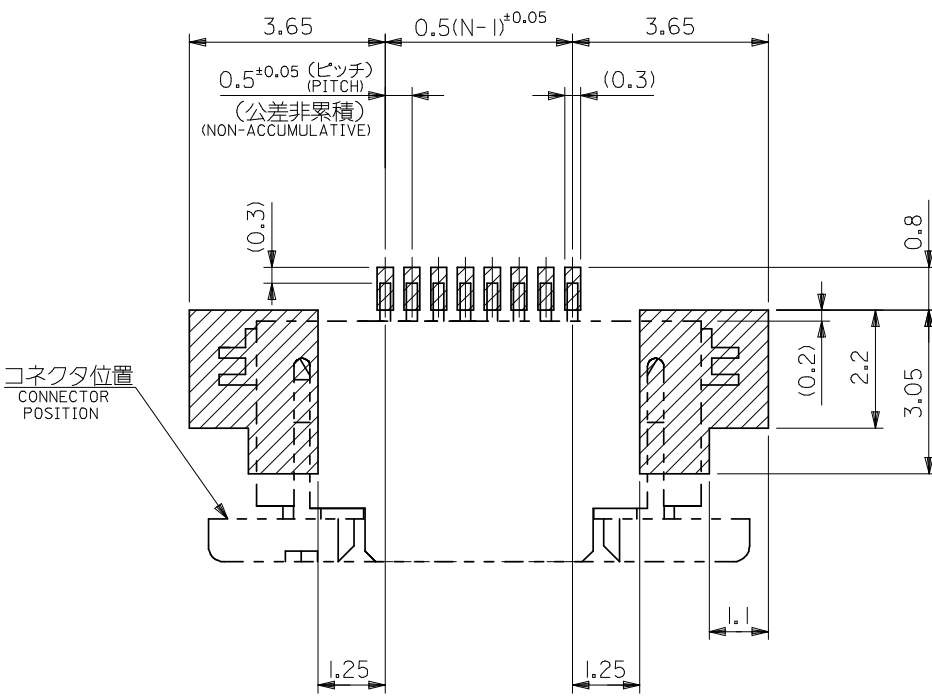
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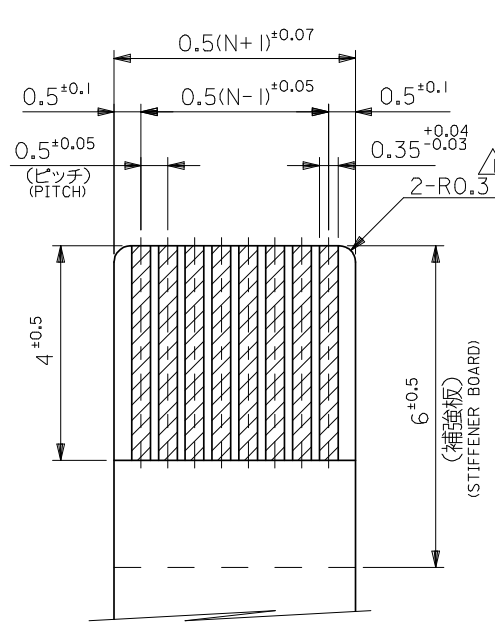
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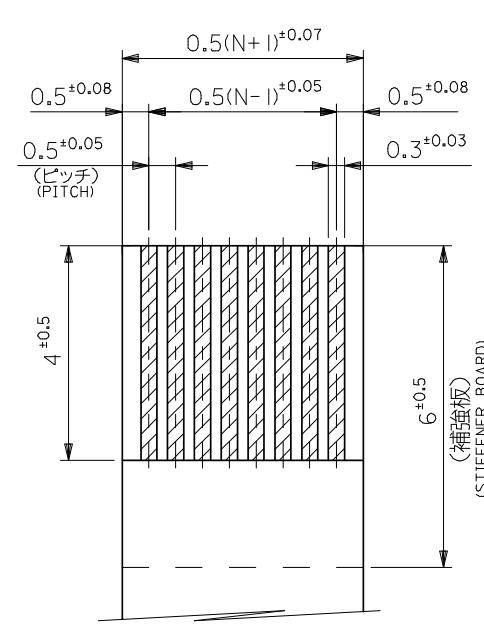
参考基板レイアウト
P.C.BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)

注記 NOTES

△ R.O. 3は、FPCの導体部にかからないこと。
R.O.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



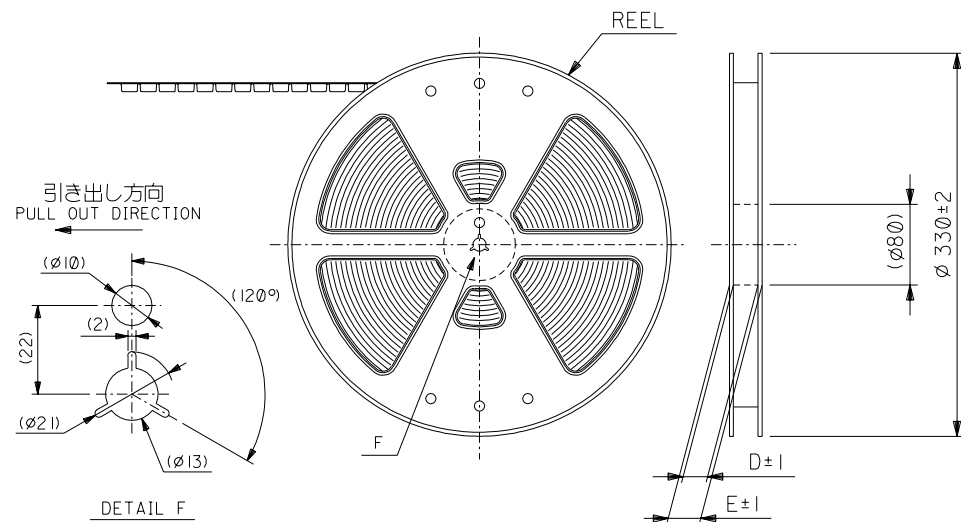
適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC :
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

52745-**19 | MODEL NO.

REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARYAWA APPR:NUKITA	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30	REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION				
			10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/01/28	TITLE 0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE-						
			10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/01/28							
			30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/01/28	 MOLEX INCORPORATED						
			ANGULAR ±3 °		MATERIAL NO.					DOCUMENT NO.		SHEET NO.	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1					SD-52745-048		2 OF 2	
					SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



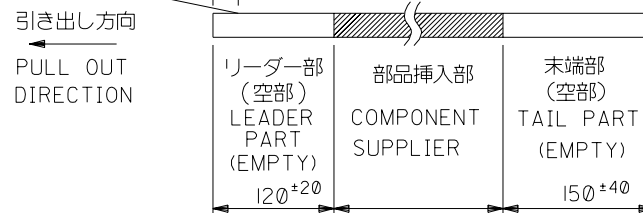
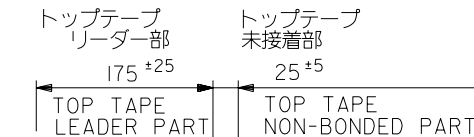
5. 材料 キャリアテープ: ポリプロピレン (PP)
 トップテープ: PET, PE, PEF
 リール: ポリスチレン (PS) <リサイクル材を含む>
MATERIAL CARRIER TAPE: POLYPROPYLENE
 TOP TAPE: PET, PE, PEF
 REEL: POLYSTYRENE (PS)
 <RECYCLE MATERIAL CONTAINED>

6. 本製品は 52745-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52745-**-90

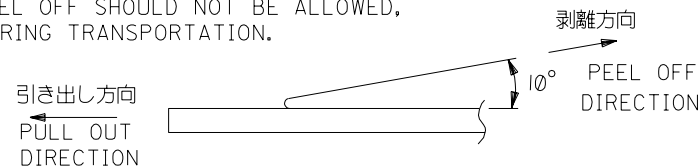
注記 NOTES

1. 製品番号 52745-**-19 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面 SD-52745-048 を参照下さい。
IN THE PACKAGE, ACTUATOR OF PART NO. 52745-**-19 SHOULD BE LOCKED
RE DETAILED DIMENSIONS, SEE SD-52745-048.

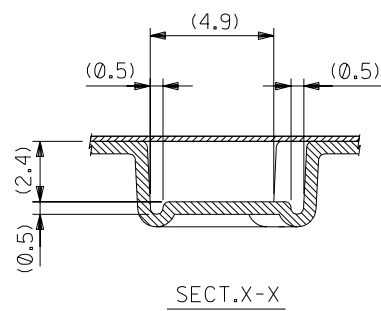
2. 梱包数量: 1000個/リール
NUMBER OF CONNECTORS: 1000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度: (剥離方向は下図参照)
0.1N~1.3N (10gf~130gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)
PEELING OFF FORCE OF TOP TAPE:
0.1N~1.3N (10gf~130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION.

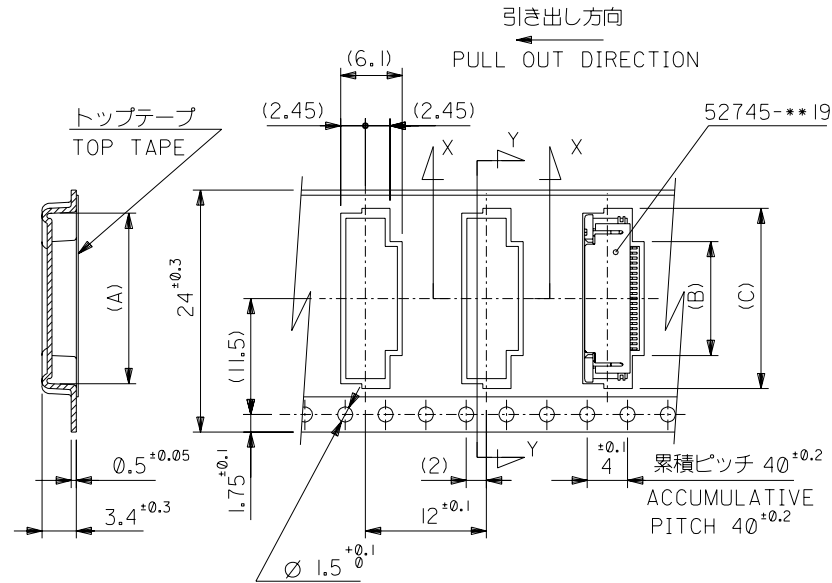


DRAWING NO. SD-52745-049		REVISED		RELEASED		MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE —//—		DESIGN UNITS ☒ mm ☐ INCH		52745-**-96 MODEL NO.		DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT REV	
DRAWN: CH'K: APPR:		DRAWN: CH'K: APPR:		DRAWN: CH'K: APPR:		FINISH 仕上げ		10 UNDER 未満		DRAWN BY & DATE T.UENO '04/01/08		CHECKED BY & DATE M.SASAO '04/01/08		TITLE: 0.5 FPC Conn Assy ZIF for SMT RA Embstp Pkg -LEAD FREE-		MOLEX MOLEX INCORPORATED		MATERIAL NO. SEE CHART	
DRAWN: CH'K: APPR:		DRAWN: CH'K: APPR:		DRAWN: CH'K: APPR:		WIRE RANGE 適用電線範囲		10 OVER 30 UNDER 以上 未満		APPROVED BY & DATE M.SASAO '04/01/08		CAD FILENAME SD-52745-049.S01		DRAWING NO. SD-52745-049		SHEET NO. 1 OF 3		INS. RANGE 被覆外径	
DRAWN: CH'K: APPR:		DRAWN: CH'K: APPR:		DRAWN: CH'K: APPR:		ANGLE 角度		30 OVER 以上		DRAWING NO. SD-52745-049		SHEET NO. 1 OF 3		SIZE B		EN-02J(097) MXJ-54		REVISE ON CAD ONLY	



DRAWN BY & DATE T.UENO '04/01/08		TITLE: 0.5 FPC Conn Assy ZIF for SMT RA Embstp Pkg -LEAD FREE-		
CHECKED BY & DATE M.SASAO '04/01/08				
APPROVED BY & DATE M.SASAO '04/01/08		MOLEX INCORPORATED		
CAD FILENAME SD-52745-049.S02	MATERIAL NO. SEE CHART	DRAWING NO. SD-52745-049	SHEET NO. 2 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B

	163NO. DRWN: CHK: APPR:	163NO. DRWN: CHK: APPR:	163NO. DRWN: CHK: APPR:	REVISED 163NO. J2004-2746 DRWN: M.NINOMIYA CHK: K.TOJO APPR: M.SASAO	RELEASED 163NO. J2004-1852 DRWN: T.UENO CHK: M.SASAO APPR: M.SASAO	MATERIAL 材料 SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3
						FINISH 仕上付 
						WIRE RANGE 適用電線範圍 
				A	Ø	REV INS. RANGE 被覆外径 



24	29.4	25.4	17.4	10.8	16.4	52745-2096	20
			16.9	10.3	15.9	- 1996	19
			16.4	9.8	15.4	- 1896	18
			15.9	9.3	14.9	- 1796	17
			15.4	8.8	14.4	- 1696	16
			14.9	8.3	13.9	- 1596	15
			14.4	7.8	13.4	- 1496	14
			13.9	7.3	12.9	- 1396	13
			13.4	6.8	12.4	- 1296	12
			12.9	6.3	11.9	- 1196	11
			12.4	5.8	11.4	- 1096	10
			11.9	5.3	10.9	- 0996	9
			11.4	4.8	10.4	- 0896	8
			10.9	4.3	9.9	- 0796	7
			10.4	3.8	9.4	52745-0696	6
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED DRAWN: J2004-2746 CH'K: M.NINOMIYA APPR: K.TOJO M.SASAO	RELEASED DRAWN: T.UENO CH'K: M.SASAO APPR: M.SASAO	DESCRIPTION REV	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE —//—	DESIGN UNITS ☒ mm ☐ INCH	☒ 1ST ANGLE PROJECTION	☐ mm INCH	☐ INCH mm	☒ mm ONLY	REVISE ON CAD ONLY
			FINISH 仕上り		10 UNDER 未満	±0.2	DRAWN BY & DATE T.UENO '04/01/08		TITLE: 0.5 FPC Conn Assy ZIF for SMT RA Embstp Pkg -LEAD FREE-			
			30 UNDER 未満		±0.25	CHECKED BY & DATE M.SASAO '04/01/08						
			WIRE RANGE 適用配線範囲		30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/01/08		MOLEX INCORPORATED			
ANGLE 角度		±3°	CAD FILENAME SD-52745-049.S03		MATERIAL NO. SEE CHART		DRAWING NO. SD-52745-049		SHEET NO. 3 OF 3			
INS. RANGE 被覆外径		DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B								